

ABSTRACT OF THE DISCLOSURE

A semiconductor laser chip unit includes an electrode pattern and a ground electrode; a semiconductor laser chip
5 which is die-bonded to the ground electrode and outputs a laser beam according to a high-frequency signal transmitted from the electrode pattern and the ground electrode, and a collimator lens for collimating the laser beam from the semiconductor laser chip. The semiconductor laser chip and
10 the collimator lens are so positioned that the laser beam output from the semiconductor laser chip is made incident on a surface of the collimator lens at a position inside of the focal point of the collimator lens, and the unit is integrated in a non-conductive heat sink so as to form a
15 unit.